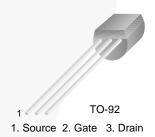


November 2013

# 2N7000BU / 2N7000TA **Advanced Small-Signal MOSFET**

## **Features**

- · Fast Switching Times
- · Improved Inductive Ruggedness
- · Lower Input Capacitance
- Extended Safe Operating Area
- · Improved High-Temperature Reliability



# Description

These N-channel enhancement mode field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. These products minimize onstate resistance while providing rugged, reliable, and fast switching performance. They can be used in most applications requiring up to 400 mA DC and can deliver pulsed currents up to 2 A. These products are particularly suited for low-voltage, low-current applications, such as small servo motor control, power MOSFET gate drivers, and other switching applications.

# **Ordering Information**

Part Number	Number Marking Package		Packing Method	
2N7000BU	2N7000	TO-92 3L	Bulk	
2N7000TA	2N7000	TO-92 3L	Ammo	

# **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at T<sub>C</sub> = 25°C unless otherwise noted.

Symbol	Parameter	Value	Unit	
V <sub>DSS</sub>	Drain-to-Source Voltage	60	V	
Continuous Drain Current (T <sub>C</sub> = 25°C)		200	mΛ	
ID	Continuous Drain Current (T <sub>C</sub> = 100°C)	110	mA	
I <sub>DM</sub>	Drain Current Pulsed <sup>(1)</sup>	1000	mA	
V <sub>GS</sub>	Gate-to-Source Voltage	±30	V	
T <sub>J,</sub> T <sub>STG</sub>	Operating Junction and Storage Temperature Range	-55 to 150	°C	
T <sub>L</sub>	Maximum Lead Temperature for Soldering Purposes,  1/8-inch from Case for 5 Seconds		°C	

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#### Note:

1. Repetitive rating: pulse width limited by maximum junction temperature.

# Thermal Characteristics(2)

Values are at  $T_C = 25$ °C unless otherwise noted.

Symbol	Parameter	Value	Unit
В	Total Power Dissipation (T <sub>C</sub> = 25°C)	400	mW
$P_{D}$	Linear Derating Factor	3.2	mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	312.5	°C/W

### Note:

2. Device mounted on FR-4 PCB, board size = 101.5 mm x 114.5 mm.

## **Electrical Characteristics**

Values are at  $T_C = 25$ °C unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 250 \mu\text{A}$	0.3		3.9	V
	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 1 \text{ mA}$	0.4		2.2	
1	Gate-Source Leakage, Forward	V <sub>GS</sub> = 15 V			100	nA
I <sub>GSS</sub>	Gate-Source Leakage, Reverse	V <sub>GS</sub> = -15 V			-100	
I <sub>DSS</sub>	Drain-to-Source Leakage Current	V <sub>DS</sub> = 60 V			1	μА
		$V_{DS} = 45 \text{ V}, T_{C} = 125^{\circ}\text{C}$			1000	
R <sub>DS(ON)</sub>	Static Drain-Source On-State Resistance <sup>(3)</sup>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 0.5 A			5.0	Ω
9 <sub>fs</sub>	Forward Transconductance <sup>(3)</sup>	$V_{DS} = 15 \text{ V}, I_{D} = 0.5 \text{ A}$	0.1	0.3		S
C <sub>iss</sub>	Input Capacitance			30		pF
C <sub>oss</sub>	Output Capacitance	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		12		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			3.0		pF
t <sub>d(on)</sub>	Turn-On Delay				10	ns
t <sub>r</sub>	Rise Time	$V_{DD} = 30 \text{ V}, I_{D} = 0.5 \text{ A},$ $R_{G} = 15 \Omega^{(3),(4)}$			10	ns
t <sub>d(off)</sub>	Turn-Off Delay	$R_G = 15 \Omega^{(3),(4)}$	/		10	ns
t <sub>f</sub>	Fall Time				10	ns

### Notes:

- 3. Pulse test: pulse width = 250  $\mu$ s, duty cycle  $\leq$  2%.
- 4. Essentially independent of operating temperature.

# **Physical Dimensions**

# TO-92

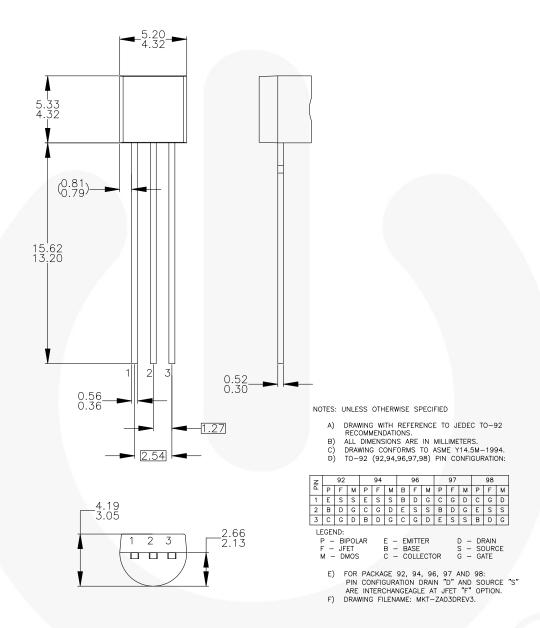


Figure 1. 3-LEAD, TO-92, JEDEC TO-92 COMPLIANT STRAIGHT LEAD CONFIGURATION

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## Physical Dimensions (Continued)

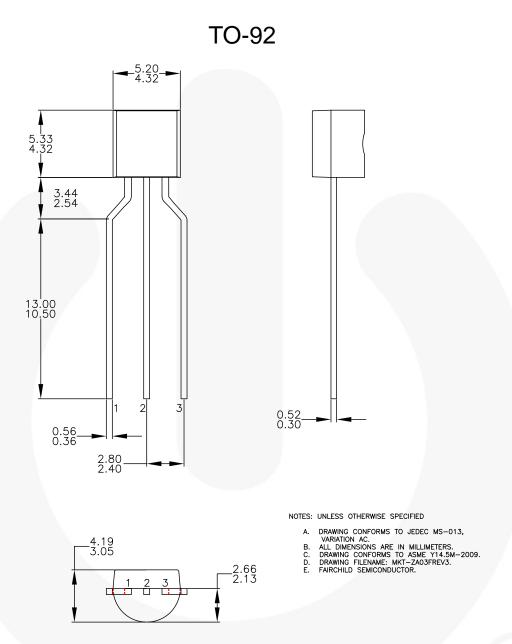


Figure 2. 3-LEAD, TO-92, MOLDED 0.200 IN LINE SPACING LD FORM (J61Z OPTION) (ACTIVE)

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